

### Low Power Peak EMI Reducing Solution

#### Features

- Generates an EMI optimized clock signal at the output.
- Integrated loop filter components.
- Operates with a 3.3V /2.5V supply.
- Operating current less than 4mA.
- Low power CMOS design.
- Input frequency : 12MHz
- Generates a 1X low EMI spread spectrum clock of the input frequency.
- Frequency deviation:  $\pm 0.4\%$ (Typ) @ 12MHz Input Frequency
- Available in 6-pin TSOT-23, 8-pin SOIC and 8-pin TSSOP packages.

The ASM3P2863A uses the most efficient and optimized modulation profile approved by the FCC and is implemented by using a proprietary all digital method.

The ASM3P2863A modulates the output of a single PLL in order to “spread” the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal’s bandwidth is called ‘spread spectrum clock generation’.

#### Applications

The ASM3P2863A is targeted towards all portable devices with very low power requirements like MP3 players, Notebooks and Digital still cameras.

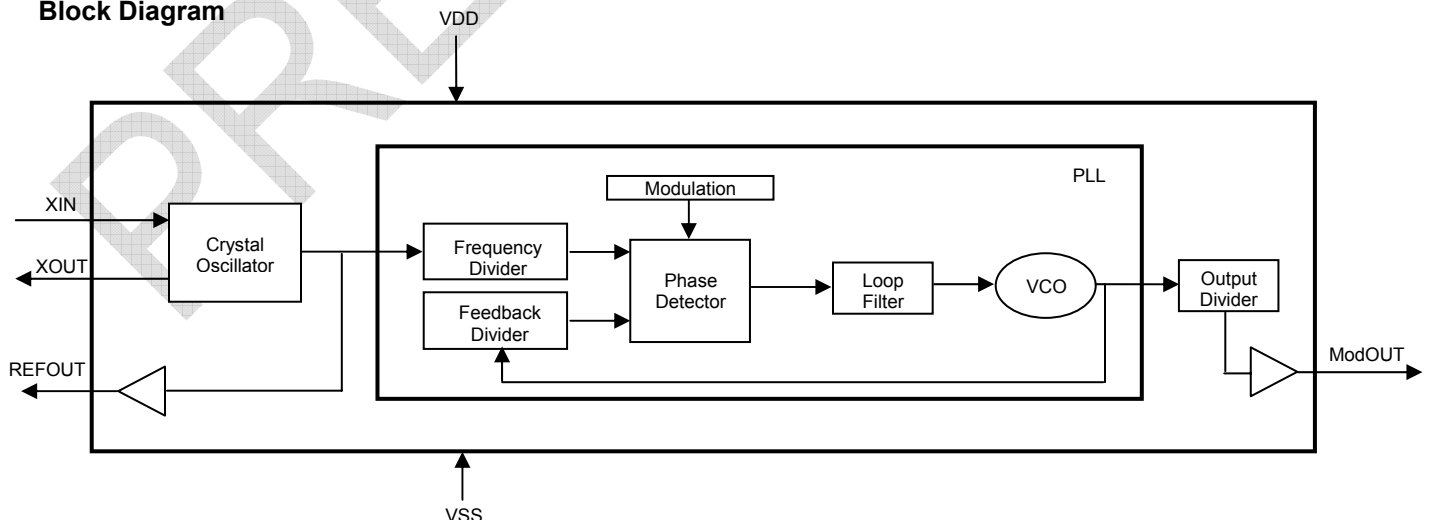
#### Product Description

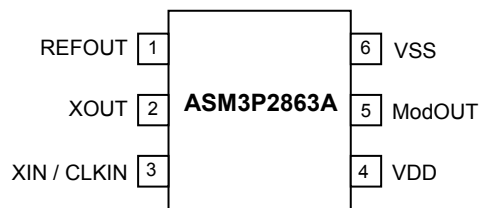
The ASM3P2863A is a versatile spread spectrum frequency modulator designed specifically for a wide range of clock frequencies. The ASM3P2863A reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of all clock dependent signals. The ASM3P2863A allows significant system cost savings by reducing the number of circuit board layers ferrite beads, shielding that are traditionally required to pass EMI regulations.

#### Key Specifications

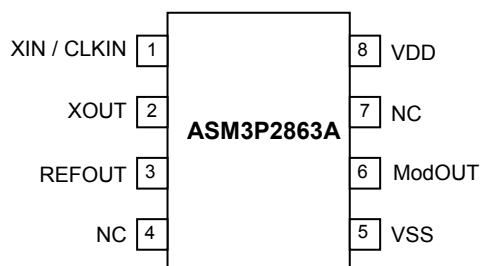
Description	Specification
Supply voltages	$V_{DD} = 2.5V / 3.3V$
Cycle-to-Cycle Jitter	200 pS ( Max)
Output Duty Cycle	45/55% (worst case)
Modulation Rate Equation	$F_{IN}/256$
Frequency Deviation	$\pm 0.4\%$ (Typ) @ 12MHz

#### Block Diagram

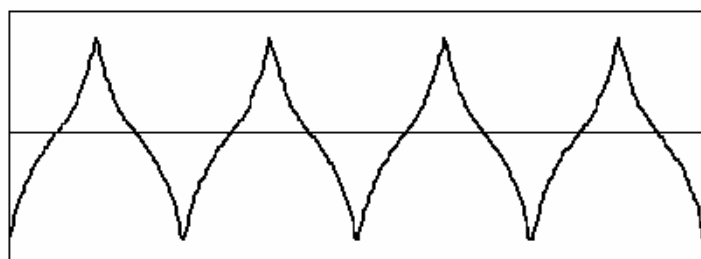


**Pin Configuration (6-pin TSOT- 23 Package)**

**Pin Description**

Pin#	Pin Name	Type	Description
1	REFOUT	O	Buffered output of the input frequency.
2	XOUT	O	Crystal connection. If using an external reference, this pin must be left unconnected.
3	XIN / CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
4	VDD	P	Power supply for the entire chip
5	ModOUT	O	Spread spectrum clock output.
6	VSS	P	Ground connection.

**Pin Configuration (8-pin SOIC and TSSOP Packages)**

**Pin Description**

Pin#	Pin Name	Type	Description
1	XIN / CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
2	XOUT	O	Crystal connection. If using an external reference, this pin must be left unconnected.
3	REFOUT	O	Buffered output of the input frequency.
4	NC	-	No connect.
5	VSS	P	Ground connection.
6	ModOUT	O	Spread spectrum clock output.
7	NC	-	No connect.
8	VDD	P	Power supply for the entire chip

**Modulation Profile**

**Specifications**

Description	Specification
Input Frequency	12MHz
Modulation Equation	$F_{IN}/256$
Frequency Deviation	$\pm 0.4\%$ ( Typ ) @ 12MHz

**rev 0.3**
**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit
VDD, V <sub>IN</sub>	Voltage on any pin with respect to Ground	-0.5 to +4.6	V
T <sub>STG</sub>	Storage temperature	-65 to +125	°C
T <sub>A</sub>	Operating temperature	0 to 70	°C
T <sub>s</sub>	Max. Soldering Temperature (10 sec)	260	°C
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>DV</sub>	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

**DC Electrical Characteristics for 2.5V Supply**

(Test condition: All parameters are measured at room temperature (+25°C) unless otherwise stated)

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>IL</sub>	Input low voltage	VSS - 0.3	-	0.8	V
V <sub>IH</sub>	Input high voltage	2.0	-	VDD + 0.3	V
I <sub>IL</sub>	Input low current	-	-	-35	μA
I <sub>IH</sub>	Input high current	-	-	35	μA
I <sub>XOL</sub>	XOUT output low current (@0.5V, VDD=2.5V)	-	3	-	mA
I <sub>XOH</sub>	XOUT output high current (@1.8V, VDD=2.5V)	-	3	-	mA
V <sub>OL</sub>	Output low voltage (VDD = 2.5V, I <sub>OL</sub> = 8 mA)	-	-	0.6	V
V <sub>OH</sub>	Output high voltage (VDD = 2.5V, I <sub>OH</sub> = 8 mA)	1.8	-	-	V
I <sub>DD</sub>	Static supply current	-	0.8	-	mA
I <sub>CC</sub>	Dynamic supply current (2.5V, 12MHz and no load)	-	3	-	mA
VDD	Operating voltage	2.375	2.5	2.625	V
t <sub>ON</sub>	Power-up time (first locked cycle after power-up)	-	-	5	mS
Z <sub>OUT</sub>	Output impedance	-	50	-	Ω

\* XIN / CLKIN pin is pulled low

**AC Electrical Characteristics for 2.5V Supply**

Symbol	Parameter	Min	Typ	Max	Unit
CLKIN	Input frequency	-	12	-	MHz
ModOUT	Output frequency	-	12	-	MHz
f <sub>d</sub>	Frequency Deviation	-	±0.4	-	%
t <sub>LH</sub> *	Output rise time (measured from 0.7V to 1.7V)	0.5	1.5	1.7	nS
t <sub>HL</sub> *	Output fall time (measured from 1.7V to 0.7V)	0.5	1.0	1.2	nS
t <sub>JC</sub>	Jitter (Cycle to Cycle)	-	200	-	pS
t <sub>D</sub>	Output duty cycle	45	50	55	%

\* t<sub>LH</sub> and t<sub>HL</sub> are measured into a capacitive load of 15pF

**DC Electrical Characteristics for 3.3V Supply**

(Test condition: All parameters are measured at room temperature (+ 25°C) unless otherwise stated)

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>IL</sub>	Input low voltage	VSS - 0.3	–	0.8	V
V <sub>IH</sub>	Input high voltage	2.0	–	VDD + 0.3	V
I <sub>IL</sub>	Input low current	–	–	-35	μA
I <sub>IH</sub>	Input high current	–	–	35	μA
I <sub>XOL</sub>	XOUT output low current (@0.4V, V <sub>DD</sub> =3.3V)	–	3	–	mA
I <sub>XOH</sub>	XOUT output high current (@2.5V, V <sub>DD</sub> =3.3V)	–	3	–	mA
V <sub>OL</sub>	Output low voltage (VDD = 3.3V, I <sub>OL</sub> = 8 mA)	–	–	0.4	V
V <sub>OH</sub>	Output high voltage (VDD = 3.3V, I <sub>OH</sub> = 8 mA)	2.5	–	–	V
I <sub>DD</sub>	Static supply current	–	1	–	mA
I <sub>CC</sub>	Dynamic supply current (3.3V, 12MHz and no load)	–	3.5	–	mA
VDD	Operating Voltage	3.0	3.3	3.6	V
t <sub>ON</sub>	Power-up time (first locked cycle after power-up)	–	–	5	mS
Z <sub>OUT</sub>	Output impedance	–	45	–	Ω

\* XIN / CLKIN pin is pulled low

**AC Electrical Characteristics for 3.3V Supply**

Symbol	Parameter	Min	Typ	Max	Unit
CLKIN	Input frequency	–	12	–	MHz
ModOUT	Output frequency	–	12	–	MHz
f <sub>d</sub>	Frequency Deviation	–	± 0.4	–	%
t <sub>LH</sub> *	Output rise time (measured from 0.8 to 2.0V)	0.5	1.4	1.6	nS
t <sub>HL</sub> *	Output fall time (measured at 2.0V to 0.8V)	0.4	1.0	1.2	nS
t <sub>JC</sub>	Jitter (Cycle to Cycle)	–	200	–	pS
t <sub>D</sub>	Output duty cycle	45	50	55	%

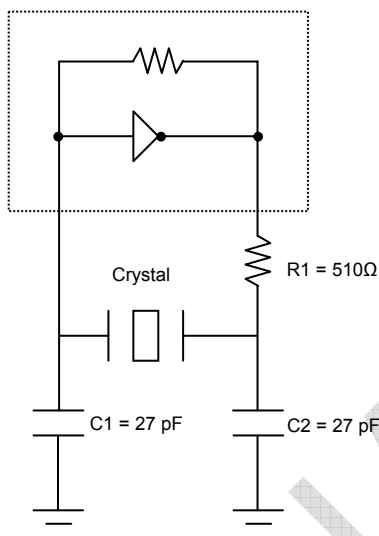
\*t<sub>LH</sub> and t<sub>HL</sub> are measured into a capacitive load of 15pF

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**ASM3P2863A**

rev 0.3

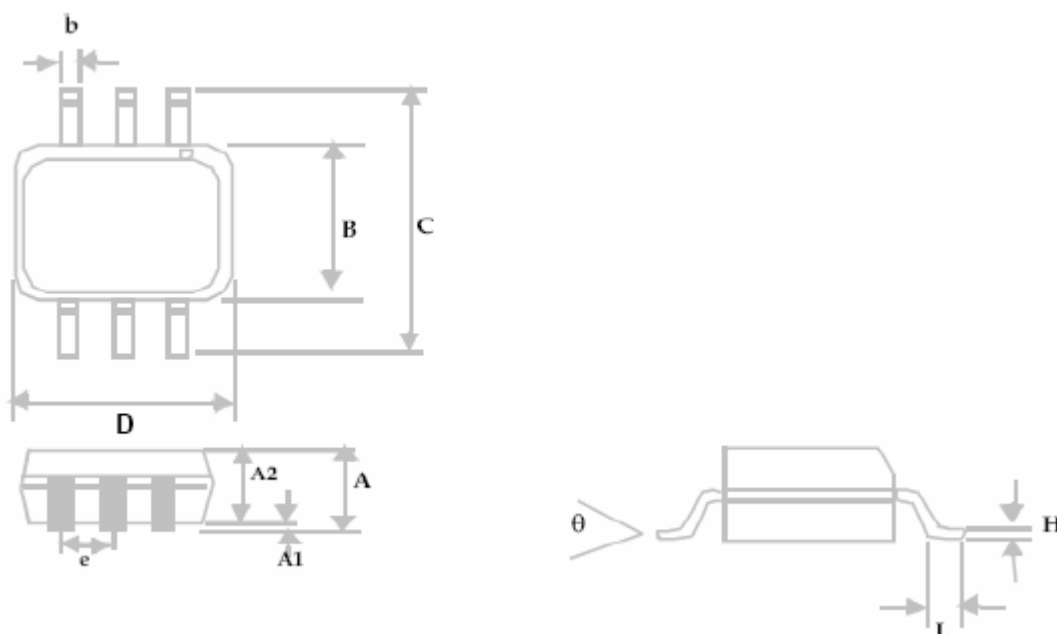
**Typical Crystal Oscillator Circuit**



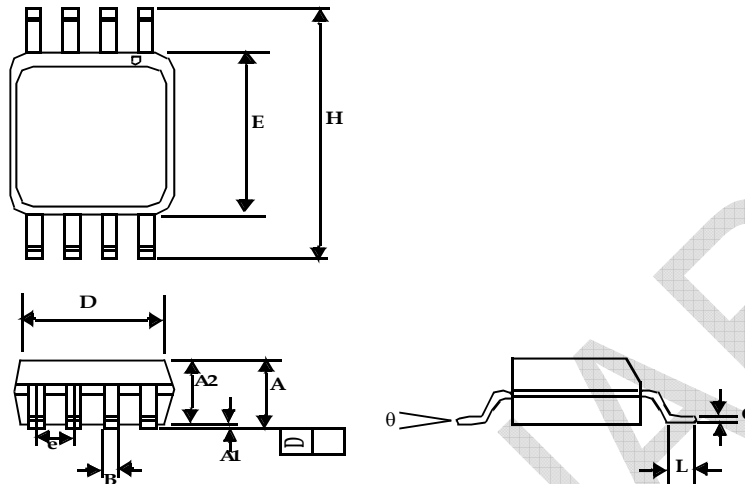
**Typical Crystal Specifications**

Fundamental AT cut parallel resonant crystal	
Nominal frequency	12.000 MHz
Frequency tolerance	± 50 ppm or better at 25°C
Operating temperature range	-25°C to +85°C
Storage temperature	-40°C to +85°C
Load capacitance	18pF
Shunt capacitance	7pF maximum
ESR	25 Ω

6-pin TSOT-23 Package



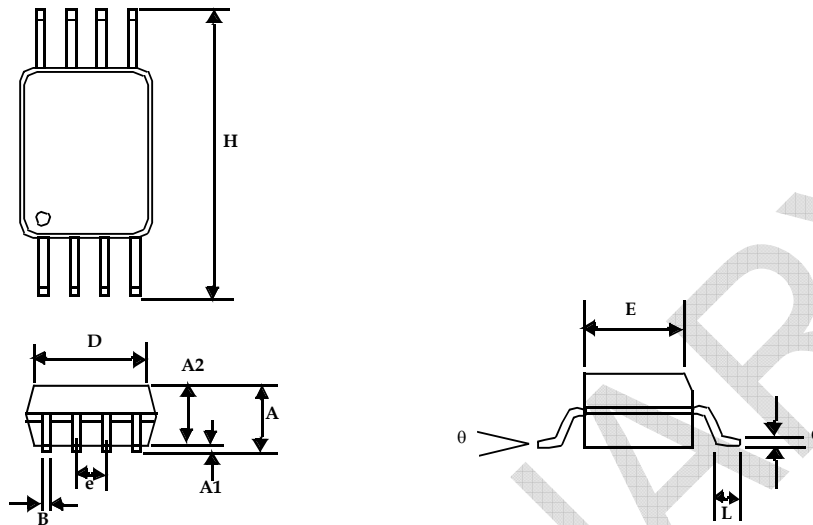
Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	.....	0.04	.....	1.00
A1	0.00	0.004	0.00	0.10
A2	0.033	0.036	0.84	0.90
b	0.012	0.02	0.30	0.50
H	0.005 BSC		0.127 BSC	
D	0.114 BSC		2.90 BSC	
B	0.06 BSC		1.60 BSC	
e	0.0374 BSC		0.950 BSC	
C	0.11 BSC		2.80 BSC	
L	0.0118	0.02	0.30	0.50
θ	0°	4°	0°	4°

**8-Pin SOIC Package**


Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A1	0.004	0.010	0.10	0.25
A	0.053	0.069	1.35	1.75
A2	0.049	0.059	1.25	1.50
B	0.012	0.020	0.31	0.51
C	0.007	0.010	0.18	0.25
D	0.193 BSC		4.90 BSC	
E	0.154 BSC		3.91 BSC	
e	0.050 BSC		1.27 BSC	
H	0.236 BSC		6.00 BSC	
L	0.016	0.050	0.41	1.27
$\theta$	0°	8°	0°	8°

**8-Pin TSSOP Package**





Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	.....	0.043	.....	1.10
A1	0.002	0.006	0.05	0.15
A2	0.033	0.037	0.85	0.95
B	0.008	0.012	0.19	0.30
c	0.004	0.008	0.09	0.20
D	0.114	0.122	2.90	3.10
E	0.169	0.177	4.30	4.50
e	0.026 BSC		0.65 BSC	
H	0.252 BSC		6.40 BSC	
L	0.020	0.028	0.50	0.70
θ	0°	8°	0°	8°

**Ordering Information**

Part Number	Marking	Package Type	Temperature
ASM3P2863AF-06OR	V4LL	6-Pin TSOT-23, TAPE & REEL, Pb Free	Commercial
ASM3P2863AF-08TT	3P2863AF	8-Pin TSSOP, TUBE, Pb Free	Commercial
ASM3P2863AF-08TR	3P2863AF	8-Pin TSSOP, TAPE & REEL, Pb Free	Commercial
ASM3P2863AF-08ST	3P2863AF	8-Pin SOIC, TUBE, Pb Free	Commercial
ASM3P2863AF-08SR	3P2863AF	8-Pin SOIC, TAPE & REEL, Pb Free	Commercial
ASM3P2863AG-06OR	V3LL	6-Pin TSOT-23, TAPE & REEL, Green	Commercial
ASM3P2863AG-08TT	3P2863AG	8-Pin TSSOP, TUBE, Green	Commercial
ASM3P2863AG-08TR	3P2863AG	8-Pin TSSOP, TAPE & REEL, Green	Commercial
ASM3P2863AG-08ST	3P2863AG	8-Pin SOIC, TUBE, Green	Commercial
ASM3P2863AG-08SR	3P2863AG	8-Pin SOIC, TAPE & REEL, Green	Commercial

**Device Ordering Information**

A S M 3 P 2 8 6 3 A F - 0 8 T R

R = Tape & Reel, T = Tube or Tray

O = TSOT23	U = MSOP	J=TSOT26
S = SOIC	E = TQFP	
T = TSSOP	L = LQFP	
A = SSOP	U = MSOP	
V = TVSOP	P = PDIP	
B = BGA	D = QSOP	
Q = QFN	X = SC-70	

DEVICE PIN COUNT

F = LEAD FREE AND RoHS COMPLIANT PART  
G = GREEN PACKAGE, LEAD FREE, and RoHS

PART NUMBER

X= Automotive (-40C to +125C)	I= Industrial (-40C to +85C)	P or n/c = Commercial (0C to +70C)
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1 = Reserved	6 = Power Management
2 = Non PLL based	7 = Power Management
3 = EMI Reduction	8 = Power Management
4 = DDR support products	9 = Hi Performance
5 = STD Zero Delav Buffer	0 = Reserved

PulseCore Semiconductor Mixed Signal Product

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Part Number: ASM3P2863A  
Document Version: 0.3

Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to PulseCore Semiconductor, dated 11-11-2003

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